THE DATASHEET OF

XC6108N34BMR

www.win-source.net 0086-755-83957316

XC6108 Series

ETR0205_010a

Voltage Detector with Separated Sense Pin & Delay Capacitor Pin

■GENERAL DESCRIPTION

The XC6108 series is highly precise, low power consumption voltage detector, manufactured using CMOS and laser trimming technologies.

Since the sense pin is separated from power supply, it allows the IC to monitor added power supply.

Using the IC with the sense pin separated from power supply enables output to maintain the state of detection even when voltage of the monitored power supply drops to 0V.

Moreover, with the built-in delay circuit, connecting the delay capacitance pin to the capacitor enables the IC to provide an arbitrary release delay time.

Both CMOS and N-channel open drain output configurations are available.

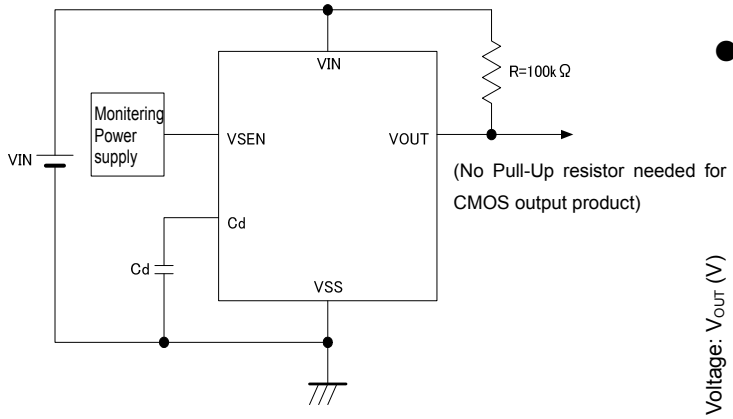
■APPLICATIONS

- ●Microprocessor reset circuitry
- ●Charge voltage monitors
- ●Memory battery back-up switch circuits
- ●Power failure detection circuits

■FEATURES

Highly Accurate	: ±2% (Detect Voltage≧1.5V) ±30mV (Detect Voltage＜1.5V)
Low Power Consumption	: 0.6 μA TYP. (detect, V_{IN}= 1.0V) 0.8 μA TYP. (release, V_{IN}= 1.0V)
Detect Voltage Range	: 0.8V ~ 5.0V in 0.1V increments
Operating Voltage Range	: 1.0V ~ 6.0V
Temperature Stability	: ±100ppm/ ℃ TYP.
Output Configuration	: CMOS or N-channel open drain
Operating Temperature	: -40 ℃ ~ +85 ℃
Separated Sense Pin	: V_{SEN} Pin Available
Built-In Delay Circuit	: Delay Time Adjustable
Packages	: USP-4, SOT-25
Environmentally Friendly	: EU RoHS Compliant, Pb Free

■TYPICAL APPLICATION CIRCUIT

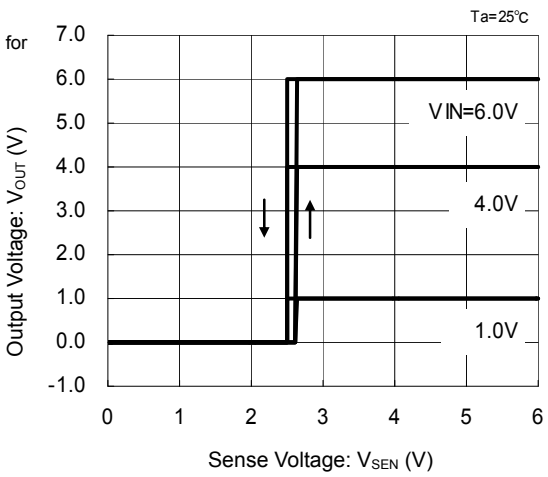


(No Pull-Up resistor needed for CMOS output product)

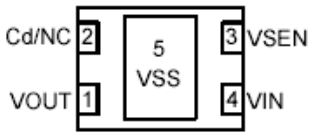
■TYPICAL PERFORMANCE CHARACTERISTICS

●Output Voltage vs. Sense Voltage

XC6108C25AGR

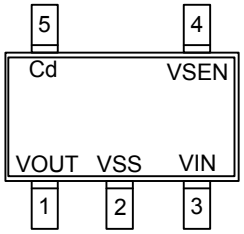


■PIN CONFIGURATION



USP-4
(BOTTOM VIEW)

* In the XC6108xxxA/B series, the dissipation pad should not be short-circuited with other pins.
* In the XC6108xxxC/D series, when the dissipation pad is short-circuited with other pins, connect it to the NC pin (No.2) pin before use.



SOT-25
(TOP VIEW)

■PIN ASSIGNMENT

PIN NUMBER		PIN NAME	FUNCTION
USP- 4	SOT-25		
1	1	VOUT	Output (Detect ”L”)
2	5	Cd	Delay Capacitance (*1)
2	-	NC	No Connection
3	4	VSEN	Sense
4	3	VIN	Input
5	2	VSS	Ground (*2)

NOTE:
*1: With the VSS pin of the USP-4 package, a tab on the backside is used as the pin No.5.
*2: In the case of selecting no built-in delay capacitance pin type, the delay capacitance (Cd) pin will be used as the N.C.

■PRODUCT CLASSIFICATION

●Ordering Information

XC6108 ①②③④⑤⑥-⑦(*1)

DESIGNATOR	DESCRIPTION	SYMBOL	DESCRIPTION
①	Output Configuration	C	CMOS output
		N	N-ch open drain output
②③	Detect Voltage	08 ~ 50	e.g. 18→1.8V
④	Output Delay & Hysteresis (Options)	A	Built-in delay capacitance pin, hysteresis 5% (TYP.)(Standard*)
		B	Built-in delay capacitance pin, hysteresis less than 1%(Standard*)
		C	No built-in delay capacitance pin, hysteresis 5% (TYP.) (Semi-custom)
		D	No built-in delay capacitance pin, hysteresis less than 1% (Semi-custom)
⑤⑥-⑦	Packages Taping Type (*2)	GR	USP-4
		GR-G	USP-4
		MR	SOT-25
		MR-G	SOT-25

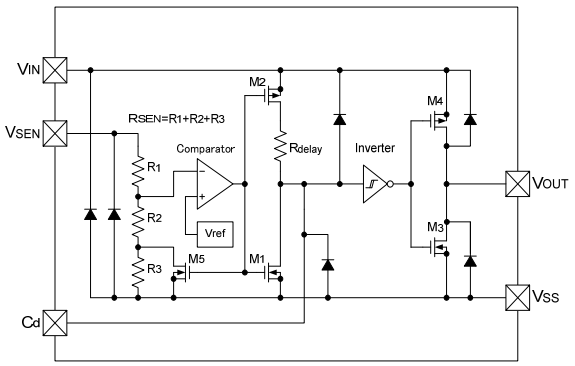
*When delay function isn’t used, open the delay capacitance pin before use.

(*1) The “-G” suffix indicates that the products are Halogen and Antimony free as well as being fully RoHS compliant.

(*2) The device orientation is fixed in its embossed tape pocket. For reverse orientation, please contact your local Torex sales office or representative. (Standard orientation: ⑤R-⑦, Reverse orientation: ⑤L-⑦)

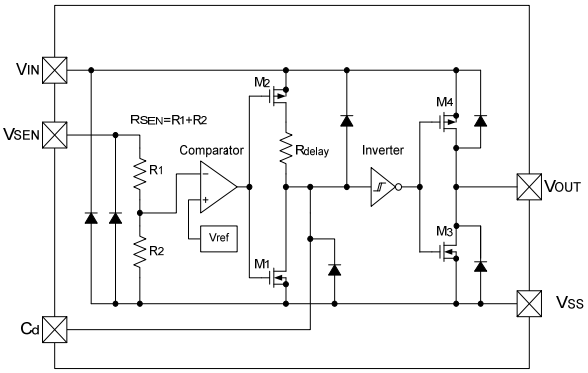
■BLOCK DIAGRAMS

(1) XC6108CxxA



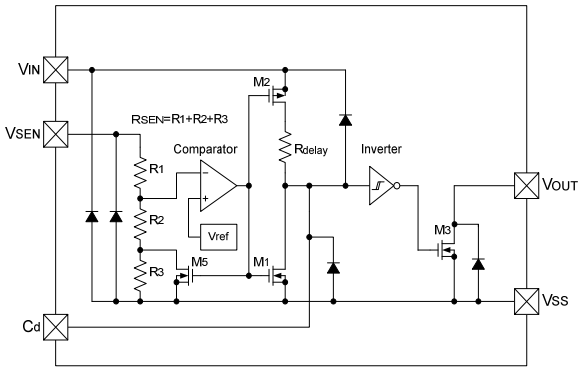
*The delay capacitance pin (Cd) is not connected to the circuit in the block diagram of XC6108CxxC (semi-custom).

(2) XC6108CxxB



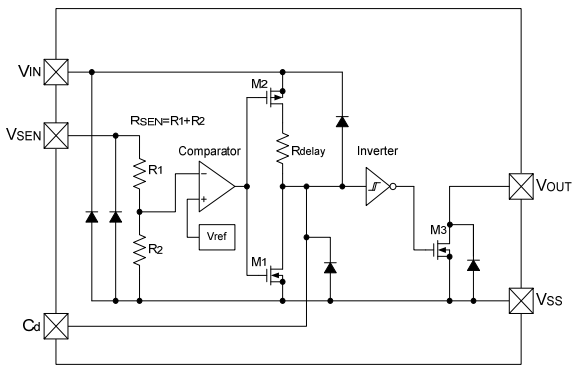
*The delay capacitance pin (Cd) is not connected to the circuit in the block diagram of XC6108CxxD (semi-custom).

(3) XC6108NxxA



*The delay capacitance pin (Cd) is not connected to the circuit in the block diagram of XC6108NxxC (semi-custom).

(4) XC6108NxxB



*The delay capacitance pin (Cd) is not connected to the circuit in the block diagram of XC6108NxxD (semi-custom).

■ABSOLUTE MAXIMUM RATINGS

●XC6108xxxA/B

Ta = 25°C

PARAMETER		SYMBOL	RATINGS	UNITS
Input Voltage		V_{IN}	V_{SS}−0.3 ~ 7.0	V
Output Current		I_{OUT}	10	mA
Output Voltage	XC6108C (*1)	V_{OUT}	V_{SS}−0.3 ~ V_{IN}+0.3	V
	XC6108N (*2)		V_{SS}−0.3 ~ 7.0	
Sense Pin Voltage		V_{SEN}	V_{SS}−0.3 ~ 7.0	V
Delay Capacitance Pin Voltage		V_{CD}	V_{SS}−0.3 ~ V_{IN}+0.3	V
Delay Capacitance Pin Current		I_{CD}	5.0	mA
Power Dissipation	USP-4	Pd	120	mW
	SOT-25		250	
Operating Temperature Range		Ta	−40 ~+85	℃
Storage Temperature Range		Tstg	−55 ~+125	℃

●XC6108xxxC/D

Ta = 25°C

PARAMETER		SYMBOL	RATINGS	UNITS
Input Voltage		V_{IN}	V_{SS}−0.3 ~ 7.0	V
Output Current		I_{OUT}	10	mA
Output Voltage	XC6108C (*1)	V_{OUT}	V_{SS}−0.3 ~ V_{IN}+0.3	V
	XC6108N (*2)		V_{SS}−0.3 ~ 7.0	
Sense Pin Voltage		V_{SEN}	V_{SS}−0.3 ~ 7.0	V
Power Dissipation	USP-4	Pd	120	mW
	SOT-25		250	
Operating Temperature Range		Ta	−40 ~+85	℃
Storage Temperature Range		Tstg	−55 ~+125	℃

NOTE:

*1: CMOS output

*2: N-ch open drain output

■ELECTRICAL CHARACTERISTICS

●XC6108xxxA

Ta=25℃

PARAMETER	SYMBOL	CONDITIONS		MIN.	TYP.	MAX.	UNITS	CIRCUITS
Operating Voltage	V_{IN}	$V_{DF(T)}$ = 0.8 ~ 5.0V (*1)		1.0	-	6.0	V	-
Detect Voltage	V_{DF}	V_{IN} = 1.0 ~ 6.0V		E-1			V	①
Hysteresis Width	V_{HYS}	V_{IN} = 1.0 ~ 6.0V		E-2			V	①
Detect Voltage Line Regulation	ΔV_{DF} / ($\Delta V_{IN} \cdot V_{DF}$)	V_{IN} = 1.0 ~ 6.0V		-	±0.1	-	%/V	①
Supply Current 1 (*2)	I_{SS1}	V_{SEN} = V_{DF} x 0.9	V_{IN} = 1.0V	-	0.6	1.5	μA	②
			V_{IN} = 6.0V	-	0.7	1.6		
Supply Current 2 (*2)	I_{SS2}	V_{SEN} = V_{DF} x 1.1	V_{IN} = 1.0V	-	0.8	1.7	μA	②
			V_{IN} = 6.0V	-	0.9	1.8		
Output Current (*3)	I_{OUT1}	V_{SEN} =0V V_{DS} = 0.5V (N-ch)	V_{IN} = 1.0V	0.1	0.7	-	mA	③
			V_{IN} = 2.0V	0.8	1.6			
			V_{IN} = 3.0V	1.2	2.0			
			V_{IN} = 4.0V	1.6	2.3			
			V_{IN} = 5.0V	1.8	2.4			
			V_{IN} = 6.0V	1.9	2.5			
	I_{OUT2}	V_{SEN} = 6.0V V_{DS} = 0.5V (P-ch)	V_{IN} = 1.0V	-	-0.30	-0.08	mA	④
			V_{IN} = 6.0V	-	-2.00	-0.70		
Leakage Current: CMOS Output	I_{LEAK}	V_{IN}=6.0V, V_{SEN}=6.0V, V_{OUT}=6.0V, Cd: Open		-	0.20	-	μA	③
Leakage Current: Nch Open Drain Output					0.20	0.40		
Temperature Characteristics	ΔV_{DF} / ($\Delta Topr \cdot V_{DF}$)	-40 ℃ ≦ Ta ≦ 85℃		-	±100	-	ppm/℃	①
Sense Resistance (*4)	R_{SEN}	V_{SEN} = 5.0V, V_{IN} = 0V		E-4			MΩ	⑤
Delay Resistance (*5)	Rdelay	V_{SEN} = 6.0V, V_{IN} = 5.0V, Cd = 0V		1.6	2.0	2.4	MΩ	⑥
Delay capacitance pin Sink Current	I_{CD}	V_{DS} = 0.5V, V_{IN} = 1.0V		-	200	-	μA	⑥
Delay Capacitance Pin Threshold Voltage	V_{TCD}	V_{SEN} = 6.0V, V_{IN} = 1.0V		0.4	0.5	0.6	V	⑦
		V_{SEN} = 6.0V, V_{IN} = 6.0V		2.9	3.0	3.1		
Unspecified Operating Voltage (*6)	V_{UNS}	V_{IN} = V_{SEN} = 0V ~ 1.0V		-	0.3	0.4	V	⑧
Detect Delay Time (*7)	t_{DF0}	V_{IN} = 6.0V, V_{SEN} = 6.0V→ 0.0V Cd: Open			30	230	μs	⑨
Release Delay Time (*8)	t_{DR0}	V_{IN} = 6.0V, V_{SEN} = 0.0V→ 6.0V Cd: Open			30	200	μs	⑨

NOTE:

*1: $V_{DF(T)}$: Nominal detect voltage

*2: Current flows the sense resistor is not included.

*3: The Pch values are applied only to the XC6108C series (CMOS output).

*4: Calculated from the voltage value and the current value of the V_{SEN}.

*5: Calculated from the voltage value of the V_{IN} and the current value of the Cd.

*6: The maximum voltage of the V_{OUT} in the range of the V_{IN} 0V to 1.0V when the V_{IN} and the V_{SEN} are short-circuited
This value is applied only to the XC6108C series (CMOS output).

*7: Time which ranges from the state of V_{SEN}=V_{DF} to the V_{OUT} reaching 0.6V when the V_{SEN} falls without connecting to the Cd pin.

*8: Time which ranges from the state of V_{IN}= V_{DF} +V_{HYS} to the V_{OUT} reaching 5.4V when the V_{SEN} rises without connecting to the Cd pin.

■ELECTRICAL CHARACTERISTICS (Continued)

●XC6108xxxB

Ta=25℃

PARAMETER	SYMBOL	CONDITIONS		MIN.	TYP.	MAX.	UNITS	CIRCUITS
Operating Voltage	V_{IN}	$V_{DF(T)}$ = 0.8 ~ 5.0V (*1)		1.0	-	6.0	V	-
Detect Voltage	V_{DF}	V_{IN} = 1.0 ~ 6.0V		E-1			V	①
Hysteresis Width	V_{HYS}	V_{IN} = 1.0 ~ 6.0V		E-3			V	①
Detect Voltage Line Regulation	ΔV_{DF} / ($\Delta V_{IN} \cdot V_{DF}$)	V_{IN} = 1.0 ~ 6.0V		-	±0.1	-	%/V	①
Supply Current 1 (*2)	I_{SS1}	V_{SEN} = V_{DF} x 0.9	V_{IN} = 1.0V	-	0.6	1.5	μA	②
			V_{IN} = 6.0V	-	0.7	1.6		
Supply Current 2 (*2)	I_{SS2}	V_{SEN} = V_{DF} x 1.1	V_{IN} = 1.0V	-	0.8	1.7	μA	②
			V_{IN} = 6.0V	-	0.9	1.8		
Output Current (*3)	I_{OUT1}	V_{SEN} =0V V_{DS} = 0.5V (N-ch)	V_{IN} = 1.0V	0.1	0.7	-	mA	③
			V_{IN} = 2.0V	0.8	1.6	-		
			V_{IN} = 3.0V	1.2	2.0			
			V_{IN} = 4.0V	1.6	2.3			
			V_{IN} = 5.0V	1.8	2.4			
			V_{IN} = 6.0V	1.9	2.5			
	I_{OUT2}	V_{SEN} = 6.0V V_{DS} = 0.5V (P-ch)	V_{IN} = 1.0V	-	-0.30	-0.08	mA	④
			V_{IN} = 6.0V	-	-2.00	-0.70		
Leakage Current: CMOS Output	I_{LEAK}	V_{IN}=6.0V, V_{SEN}=6.0V, V_{OUT}=6.0V, Cd: Open		-	0.20	-	μA	③
Leakage Current: Nch Open Drain Output					0.20	0.40		
Temperature Characteristics	ΔV_{DF} / ($\Delta Topr \cdot V_{DF}$)	-40 ℃ ≦ Ta ≦ 85℃		-	±100	-	ppm/℃	①
Sense Resistance (*4)	R_{SEN}	V_{SEN} = 5.0V, V_{IN} = 0V		E-4			MΩ	⑤
Delay Resistance (*5)	Rdelay	V_{SEN} = 6.0V, V_{IN} = 5.0V, Cd = 0V		1.6	2.0	2.4	MΩ	⑥
Delay capacitance pin Sink Current	I_{CD}	V_{DS} = 0.5V, V_{IN} = 1.0V		-	200	-	μA	⑥
Delay Capacitance Pin Threshold Voltage	V_{TCD}	V_{SEN} = 6.0V, V_{IN} = 1.0V		0.4	0.5	0.6	V	⑦
		V_{SEN} = 6.0V, V_{IN} = 6.0V		2.9	3.0	3.1		
Unspecified Operating Voltage (*6)	V_{UNS}	V_{IN} = V_{SEN} = 0V ~ 1.0V		-	0.3	0.4	V	⑧
Detect Delay Time (*7)	t_{DF0}	V_{IN} = 6.0V, V_{SEN} = 6.0V→ 0.0V Cd: Open			30	230	μs	⑨
Release Delay Time (*8)	t_{DR0}	V_{IN} = 6.0V, V_{SEN} = 0.0V→ 6.0V Cd: Open			30	200	μs	⑨

NOTE:

*1: $V_{DF(T)}$: Nominal detect voltage

*2: Current flows the sense resistor is not included.

*3: The Pch values are applied only to the XC6108C series (CMOS output).

*4: Calculated from the voltage value and the current value of the V_{SEN}.

*5: Calculated from the voltage value of the V_{IN} and the current value of the Cd.

*6: The maximum voltage of the V_{OUT} in the range of the V_{IN} 0V to 1.0V when the V_{IN} and the V_{SEN} are short-circuited
This value is applied only to the XC6108C series (CMOS output).

*7: Time which ranges from the state of V_{SEN}=V_{DF} to the V_{OUT} reaching 0.6V when the V_{SEN} falls without connecting to the Cd pin.

*8: Time which ranges from the state of V_{IN}= V_{DF} +V_{HYS} to the V_{OUT} reaching 5.4V when the V_{SEN} rises without connecting to the Cd pin.

■ELECTRICAL CHARACTERISTICS (Continued)

●XC6108xxxC

Ta=25℃

PARAMETER	SYMBOL	CONDITIONS		MIN.	TYP.	MAX.	UNITS	CIRCUITS
Operating Voltage	V_{IN}	$V_{DF(T)}$ = 0.8 ~ 5.0V (*1)		1.0	-	6.0	V	-
Detect Voltage	V_{DF}	V_{IN} = 1.0 ~ 6.0V		E-1			V	①
Hysteresis Width	V_{HYS}	V_{IN} = 1.0 ~ 6.0V		E-2			V	①
Detect Voltage Line Regulation	ΔV_{DF} / ($\Delta V_{IN} \cdot V_{DF}$)	V_{IN} = 1.0 ~ 6.0V		-	±0.1	-	%/V	①
Supply Current 1 (*2)	I_{SS1}	V_{SEN} = V_{DF} x 0.9	V_{IN} = 1.0V	-	0.6	1.5	μA	②
			V_{IN} = 6.0V	-	0.7	1.6		
Supply Current 2 (*2)	I_{SS2}	V_{SEN} = V_{DF} x 1.1	V_{IN} = 1.0V	-	0.8	1.7	μA	②
			V_{IN} = 6.0V	-	0.9	1.8		
Output Current (*3)	I_{OUT1}	V_{SEN} =0V V_{DS} = 0.5V (N-ch)	V_{IN} = 1.0V	0.1	0.7	-	mA	③
			V_{IN} = 2.0V	0.8	1.6			
			V_{IN} = 3.0V	1.2	2.0			
			V_{IN} = 4.0V	1.6	2.3			
			V_{IN} = 5.0V	1.8	2.4			
			V_{IN} = 6.0V	1.9	2.5			
	I_{OUT2}	V_{SEN} = 6.0V V_{DS} = 0.5V (P-ch)	V_{IN} = 1.0V	-	-0.30	-0.08	mA	④
			V_{IN} = 6.0V	-	-2.00	-0.70		
Leakage Current: CMOS Output	I_{LEAK}	V_{IN}=6.0V, V_{SEN}=6.0V, V_{OUT}=6.0V, Cd: Open		-	0.20	-	μA	③
Leakage Current: Nch Open Drain Output					0.20	0.40		
Temperature Characteristics	ΔV_{DF}/ ($\Delta Topr \cdot V_{DF}$)	-40 ℃ ≦ Ta ≦ 85℃		-	±100	-	ppm/℃	①
Sense Resistance (*4)	R_{SEN}	V_{SEN} = 5.0V, V_{IN} = 0V		E-4			MΩ	⑤
Unspecified Operating Voltage (*5)	V_{UNS}	V_{IN} = V_{SEN} = 0V ~ 1.0V		-	0.3	0.4	V	⑦
Detect Delay Time (*6)	t_{DF0}	V_{IN} = 6.0V, V_{SEN} = 6.0V→ 0.0V			30	230	μs	⑨
Release Delay Time (*7)	t_{DR0}	V_{IN} = 6.0V, V_{SEN} = 0.0V→ 6.0V			30	200	μs	⑨

NOTE:

*1: $V_{DF(T)}$: Nominal detect voltage

*2: Current flows the sense resistor is not included.

*3: The Pch values are applied only to the XC6108C series (CMOS output).

*4: Calculated from the voltage value and the current value of the V_{SEN}.

*5: The maximum voltage of the V_{OUT} in the range of the V_{IN} 0V to 1.0V when the V_{IN} and the V_{SEN} are short-circuited
This value is applied only to the XC6108C series (CMOS output).

*6: Time which ranges from the state of V_{SEN}=V_{DF} to the V_{OUT} reaching 0.6V when the V_{SEN} falls.

*7: Time which ranges from the state of V_{IN}= V_{DF} +V_{HYS} to the V_{OUT} reaching 5.4V when the V_{SEN} rises.

■ELECTRICAL CHARACTERISTICS (Continued)

●XC6108xxxD

Ta=25℃

PARAMETER	SYMBOL	CONDITIONS		MIN.	TYP.	MAX.	UNITS	CIRCUITS
Operating Voltage	V_{IN}	$V_{DF(T)}$ = 0.8 ~ 5.0V (*1)		1.0	-	6.0	V	-
Detect Voltage	V_{DF}	V_{IN} = 1.0 ~ 6.0V		E-1			V	1
Hysteresis Width	V_{HYS1}	V_{IN} = 1.0 ~ 6.0V		E-3			V	1
Detect Voltage Line Regulation	ΔV_{DF} / ($\Delta V_{IN} \cdot V_{DF}$)	V_{IN} = 1.0 ~ 6.0V		-	±0.1	-	%/V	1
Supply Current 1 (*2)	I_{SS1}	V_{SEN} = V_{DF} x 0.9	V_{IN} = 1.0V	-	0.6	1.5	μA	2
			V_{IN} = 6.0V	-	0.7	1.6		
Supply Current 2 (*2)	I_{SS2}	V_{SEN} = V_{DF} x 1.1	V_{IN} = 1.0V	-	0.8	1.7	μA	2
			V_{IN} = 6.0V	-	0.9	1.8		
Output Current (*3)	I_{OUT1}	V_{SEN} =0V V_{DS} = 0.5V (N-ch)	V_{IN} = 1.0V	0.1	0.7	-	mA	3
			V_{IN} = 2.0V	0.8	1.6			
			V_{IN} = 3.0V	1.2	2.0			
			V_{IN} = 4.0V	1.6	2.3			
			V_{IN} = 5.0V	1.8	2.4			
			V_{IN} = 6.0V	1.9	2.5			
	I_{OUT2}	V_{SEN} = 6.0V V_{DS} = 0.5V (P-ch)	V_{IN} = 1.0V	-	-0.30	-0.08	mA	4
			V_{IN} = 6.0V	-	-2.00	-0.70		
Leakage Current: CMOS Output	I_{LEAK}	V_{IN}=6.0V, V_{SEN}=6.0V, V_{OUT}=6.0V, Cd: Open		-	0.20	-	μA	3
Leakage Current: Nch Open Drain Output					0.20	0.40		
Temperature Characteristics	ΔV_{DF} / ($\Delta Topr \cdot V_{DF}$)	-40 ℃ ≦ Ta ≦ 85℃		-	±100	-	ppm/℃	1
Sense Resistance (*4)	R_{SEN}	V_{SEN} = 5.0V, V_{IN} = 0V		E-4			MΩ	5
Unspecified Operating Voltage (*5)	V_{UNS}	V_{IN} = V_{SEN} = 0V ~ 1.0V		-	0.3	0.4	V	7
Detect Delay Time (*6)	t_{DF0}	V_{IN} = 6.0V, V_{SEN} = 6.0V→ 0.0V			30	230	μs	9
Release Delay Time (*7)	t_{DR0}	V_{IN} = 6.0V, V_{SEN} = 0.0V→ 6.0V			30	200	μs	9

NOTE:

*1: $V_{DF(T)}$: Nominal detect voltage

*2: Current flows the sense resistor is not included.

*3: The Pch values are applied only to the XC6108C series (CMOS output).

*4: Calculated from the voltage value and the current value of the V_{SEN}.

*5: The maximum voltage of the V_{OUT} in the range of the V_{IN} 0V to 1.0V when the V_{IN} and the V_{SEN} are short-circuited
This value is applied only to the XC6108C series (CMOS output).

*6: Time which ranges from the state of V_{SEN}=V_{DF} to the V_{OUT} reaching 0.6V when the V_{SEN} falls.

*7: Time which ranges from the state of V_{IN}= V_{DF} +V_{HYS} to the V_{OUT} reaching 5.4V when the V_{SEN} rises.

■VOLTAGE CHART

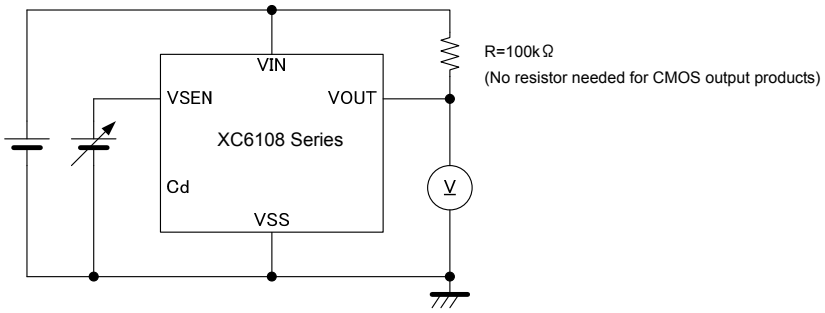
SYMBOL	E-1		E-2		E-3		E-4	
NOMINAL DETECT VOLTAGE	DETECT VOLTAGE (*1) (V)		HYSTERESIS RANGE (V)		HYSTERESIS RANGE (V)		SENSE RESISTANCE (MΩ)	
$V_{DF(T)}$ (V)	V_{DF}		V_{HYS}		V_{HYS}		R_{SEN}	
	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	TYP.
0.8	0.770	0.830	0.015	0.066		0.008		
0.9	0.870	0.930	0.017	0.074		0.009		
1.0	0.970	1.030	0.019	0.082		0.010		
1.1	1.070	1.130	0.021	0.090		0.011		
1.2	1.170	1.230	0.023	0.098		0.012		
1.3	1.270	1.330	0.025	0.106		0.013	10	20
1.4	1.370	1.430	0.027	0.114		0.014		
1.5	1.470	1.530	0.029	0.122		0.015		
1.6	1.568	1.632	0.031	0.131		0.016		
1.7	1.666	1.734	0.033	0.085		0.017		
1.8	1.764	1.836	0.035	0.147		0.018		
1.9	1.862	1.938	0.037	0.155		0.019		
2.0	1.960	2.040	0.039	0.163		0.020		
2.1	2.058	2.142	0.041	0.171		0.021		
2.2	2.156	2.244	0.043	0.180		0.022		
2.3	2.254	2.346	0.045	0.188		0.023		
2.4	2.352	2.448	0.047	0.196		0.024		
2.5	2.450	2.550	0.049	0.204		0.026		
2.6	2.548	2.652	0.051	0.212		0.027		
2.7	2.646	2.754	0.053	0.220		0.028		
2.8	2.744	2.856	0.055	0.228		0.029		
2.9	2.842	2.958	0.057	0.237	0	0.030	13	24
3.0	2.940	3.060	0.059	0.245		0.031		
3.1	3.038	3.162	0.061	0.253		0.032		
3.2	3.136	3.264	0.063	0.261		0.033		
3.3	3.234	3.366	0.065	0.269		0.034		
3.4	3.332	3.468	0.067	0.277		0.035		
3.5	3.430	3.570	0.069	0.286		0.036		
3.6	3.528	3.672	0.071	0.294		0.037		
3.7	3.626	3.774	0.073	0.302		0.038		
3.8	3.724	3.876	0.074	0.310		0.039		
3.9	3.822	3.978	0.076	0.318		0.040		
4.0	3.920	4.080	0.078	0.326		0.041		
4.1	4.018	4.182	0.080	0.335		0.042		
4.2	4.116	4.284	0.082	0.343		0.043		
4.3	4.214	4.386	0.084	0.351		0.044		
4.4	4.312	4.488	0.086	0.359		0.045		
4.5	4.410	4.590	0.088	0.367		0.046	15	28
4.6	4.508	4.692	0.090	0.375		0.047		
4.7	4.606	4.794	0.092	0.384		0.048		
4.8	4.704	4.896	0.094	0.392		0.049		
4.9	4.802	4.998	0.096	0.400		0.050		
5.0	4.900	5.100	0.098	0.408		0.051		

NOTE:

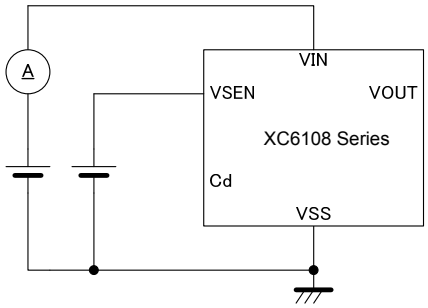
*1: When $V_{DF(T)} \leqq 1.4V$, the detection accuracy is ±30mV.
When $V_{DF(T)} \geqq 1.5V$, the detection accuracy is ±2%.

■TEST CIRCUITS

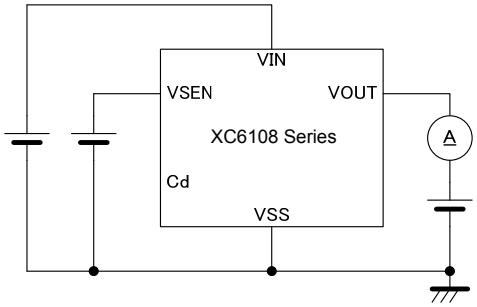
Circuit 1



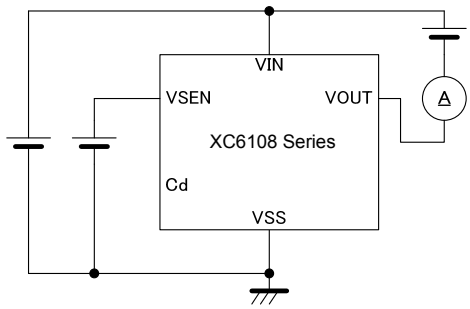
Circuit 2



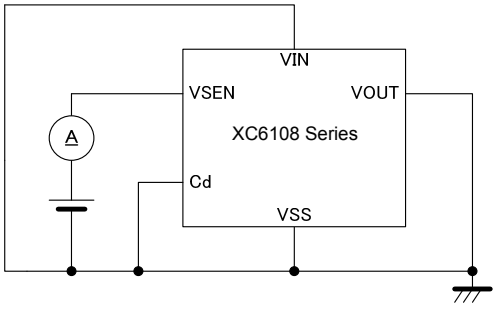
Circuit 3



Circuit 4

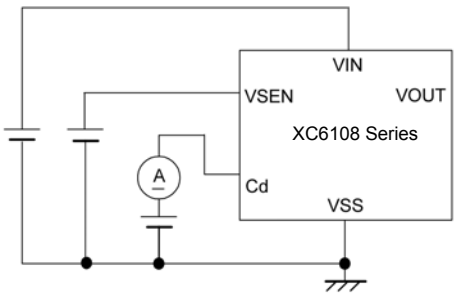


Circuit 5

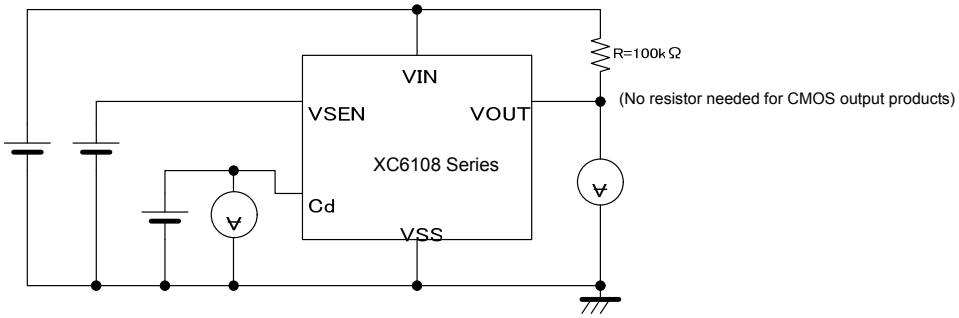


■TEST CIRCUITS (Continued)

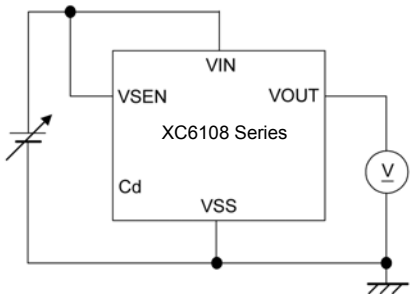
Circuit 6



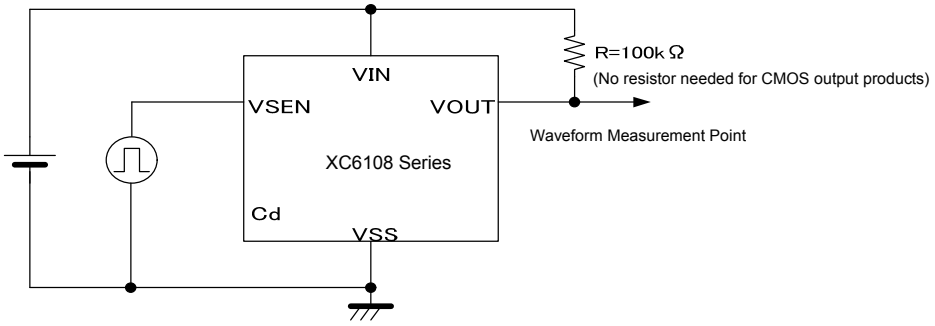
Circuit 7



Circuit 8



Circuit 9



*No delay capacitance pin available in the XC6108xxxC/D series.

■OPERATIONAL EXPLANATION

A typical circuit example is shown in Figure 1, and the timing chart of Figure 1 is shown in Figure 2 on page 14.

① As an early state, the sense pin is applied sufficiently high voltage (6.0V MAX.) and the delay capacitance (Cd) is charged to the power supply input voltage, (V_{IN}: 1.0V MIN., 6.0V MAX.). While the sense pin voltage (V_{SEN}) starts dropping to reach the detect voltage (V_{DF}) (V_{SEN}>V_{DF}), the output voltage (V_{OUT}) keeps the "High" level (=V_{IN}).
* If a pull-up resistor of the XC6108N series (N-ch open drain) is connected to added power supply different from the input voltage pin, the "High" level will be a voltage value where the pull-up resistor is connected.

② When the sense pin voltage keeps dropping and becomes equal to the detect voltage (V_{SEN} =V_{DF}), an N-ch transistor (M1) for the delay capacitance (Cd) discharge is turned ON, and starts to discharge the delay capacitance (Cd). An inverter (Inv.1) operates as a comparator of the reference voltage V_{IN}, and the output voltage changes into the "Low" level (=V_{SS}). The detect delay time [t_{DF}] is defined as time which ranges from V_{SEN}=V_{DF} to the V_{OUT} of "Low" level (especially, when the Cd pin is not connected: t_{DF0}).

③ While the sense pin voltage keeps below the detect voltage, the delay capacitance (Cd) is discharged to the ground voltage (=V_{SS}) level. Then, the output voltage maintains the "Low" level while the sense pin voltage increases again to reach the release voltage (V_{SEN}< V_{DF} +V_{HYS}).

④ When the sense pin voltage continues to increase up to the release voltage level (V_{DF}+V_{HYS}), the N-ch transistor (M1) for the delay capacitance (Cd) discharge will be turned OFF, and the delay capacitance (Cd) will start discharging via a delay resistor (Rdelay). The inverter (Inv.1) will operate as a comparator (Rise Logic Threshold: V_{TLH}=V_{TCD}, Fall Logic Threshold: V_{THL}=V_{SS}) while the sense pin voltage keeps higher than the detect voltage (V_{SEN} > V_{DF}).

⑤ While the delay capacitance pin voltage (V_{CD}) rises to reach the delay capacitance pin threshold voltage (V_{TCD}) with the sense pin voltage equal to the release voltage or higher, the sense pin will be charged by the time constant of the RC series circuit. Assuming the time to the release delay time (t_{DR}), it can be given by the formula (1).

$$t_{DR} = -Rdelay \times Cd \times In\,(1 - V_{TCD} / V_{IN}) \quad \cdots(1)$$

* In = a natural logarithm

The release delay time can also be briefly calculated with the formula (2) because the delay resistance is 2.0MΩ (TYP.) and the delay capacitance pin voltage is V_{IN} /2 (TYP.)

$$t_{DR} = Rdelay \times Cd \times 0.69 \cdots(2)$$

∗ : Rdelay is 2.0MΩ （TYP.）

As an example, presuming that the delay capacitance is 0.68μF, t_{DR} is :

$$2.0 \times 10^{6} \times 0.68 \times 10^{-6} \times 0.69 = 938(ms)$$

* Note that the release delay time may remarkably be short when the delay capacitance (Cd) is not discharged to the ground (=VSS) level because time described in ③ is short.

⑥ When the delay capacitance pin voltage reaches to the delay capacitance pin threshold voltage (V_{CD}=V_{TCD}), the inverter (Inv.1) will be inverted. As a result, the output voltage changes into the "High" (=V_{IN}) level. t_{DR0} is defined as time which ranges from V_{SEN}=V_{DF}+V_{HYS} to the V_{OUT} of "High" level without connecting to the Cd.

⑦ While the sense voltage is higher than the detect voltage (V_{SEN} > V_{DF}), the delay capacitance pin is charged until the delay capacitance pin voltage becomes the input voltage level. Therefore, the output voltage maintains the "High"(=V_{IN}) level.

■OPERATIONAL EXPLANATION (Continued)

●Function Chart

V_{SEN}	Cd	TRANSITION OF V_{OUT} CONDITION *1		
		①		②
L	L	L	⇒	L
	H			
	L	H		
	H			
H	L	L	⇒	L
	H		⇒	H
	L	H	⇒	
	H			

*1: VOUT transits from condition ① to ② because of the combination of VSEN and Cd.

●Example

ex. 1) V_{OUT} ranges from 'L' to 'H' in case of VSEN = 'H' (VDR≧VSEN), Cd='H' (VTCD≧Cd) while VOUT is 'L'.

ex. 2) V_{OUT} maintains 'H' when Cd ranges from 'H' to 'L', VSEN='H' and Cd='L' when V_{OUT} becomes 'H' in ex.1.

●Release Delay Time Chart

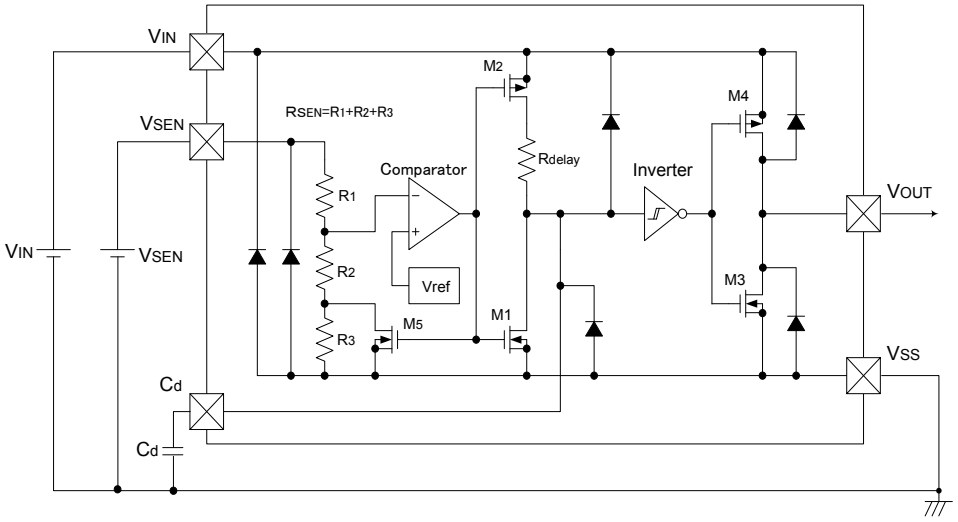
DELAY CAPACITANCE [Cd] (μF)	RELEASE DELAY TIME [t_{DR}] (TYP.) (ms)	RELEASE DELAY TIME [t_{DR}] *2 (MIN. ~ MAX.) (ms)
0.010	13.8	11.0 ~ 16.6
0.022	30.4	24.3 ~ 36.4
0.047	64.9	51.9 ~ 77.8
0.100	138	110 ~ 166
0.220	304	243~ 364
0.470	649	519 ~ 778
1.000	1380	1100 ~ 1660

* The release delay time values above are calculated by using the formula (2).

*2: The release delay time (t_{DR}) is influenced by the delay capacitance Cd.

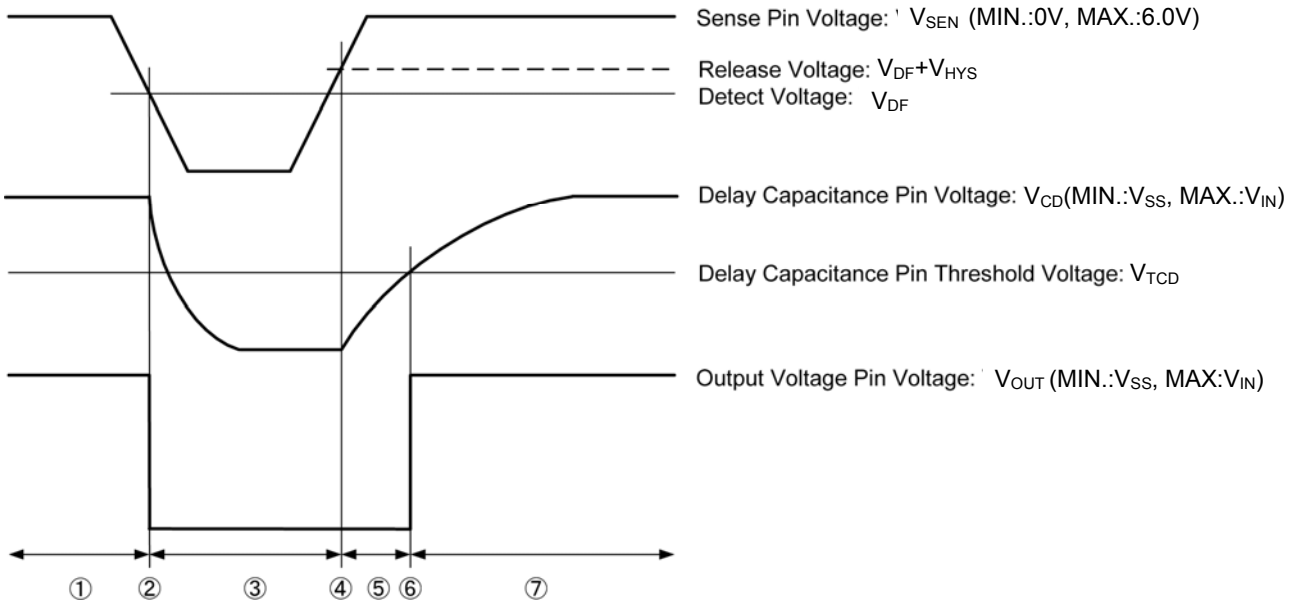
■OPERATIONAL EXPLANATION (Continued)

Figure 1: Typical application circuit example



*The XC6108N series (N-ch open drain output) requires a pull-up resistor for pulling up output.

Figure 2: The timing chart of Figure 1



■NOTES ON USE

1. Use this IC within the stated maximum ratings. Operation beyond these limits may cause degrading or permanent damage to the device.
2. The power supply input pin voltage drops by the resistance between power supply and the VIN pin, and by through current at operation of the IC. At this time, the operation may be wrong if the power supply input pin voltage falls below the minimum operating voltage range. In CMOS output, for output current, drops in the power supply input pin voltage similarly occur. Moreover, in CMOS output, when the VIN pin and the sense pin are short-circuited and used, oscillation of the circuit may occur if the drops in voltage, which caused by through current at operation of the IC, exceed the hysteresis voltage. Note it especially when you use the IC with the VIN pin connected to a resistor.
3. When the setting voltage is less than 1.0V, be sure to separate the VIN pin and the sense pin, and to apply the voltage over 1.0V to the VIN pin.
4. Note that a rapid and high fluctuation of the power supply input pin voltage may cause a wrong operation.
5. Power supply noise may cause operational function errors, Care must be taken to put the capacitor between V_{IN}-GND and test on the board carefully.
6. When there is a possibility of which the power supply input pin voltage falls rapidly (e.g.: 6.0V to 0V) at release operation with the delay capacitance pin (Cd) connected to a capacitor, use a schottky barrier diode connected between the VIN pin and the Cd pin as the Figure 3 shown below.

6. In N channel open drain output, V_{OUT} voltage at detect and release is determined by resistance of a pull up resistor connected at the V_{OUT} pin. Please choose proper resistance values with reffering to Figure 4;

During detection : V_{OUT} = Vpull / (1+Rpull / R_{ON})
Vpull: Pull up voltage
R_{ON}(※1) : On resistance of N channel driver M3 can be calculated as V_{DS} / I_{OUT1} from electrical characteristics,
For example, when (※2) R_{ON} = 0.5 / 0.8 × 10^{-3} = 625Ω （MIN.） at V_{IN}=2.0V, Vpull = 3.0V and V_{OUT} ≦0.1V at detect,
Rpull= (Vpull /V_{OUT}-1) × R_{ON}= (3 / 0.1-1) × 625≒18ｋΩ
In this case, Rpull should be selected higher or equal to 18kΩ in order to keep the output voltage less than 0.1V during detection.
(※1) R_{ON} is bigger when V_{IN} is smaller, be noted.
(※2) For calculation, Minimum V_{IN} should be chosen among the input voltage range.

During releasing : V_{OUT} = Vpull / (1 + Rpull / Roff)
Vpull : Pull up voltage
Roff : On resistance of N channel driver M3 is 15MΩ （MIN.） when the driver is off (as to V_{OUT} / I_{LEAK})
For example : when Vpull = 6.0V and V_{OUT} ≧ 5.99V,
Rpull = (Vpull / V_{OUT}-1) × Roff = (6/5.99-1) × 15 × 10^6 ≒25kΩ
In this case, Rpull should be selected smaller or equal to 25kΩ in order to obtain output voltage higher than 5.99V during releasing.

Figure 3: Circuit example with the delay capacitance pin (Cd) connected to a schottky barrier diode
Figure 4: Circuit example of XC6108N Series

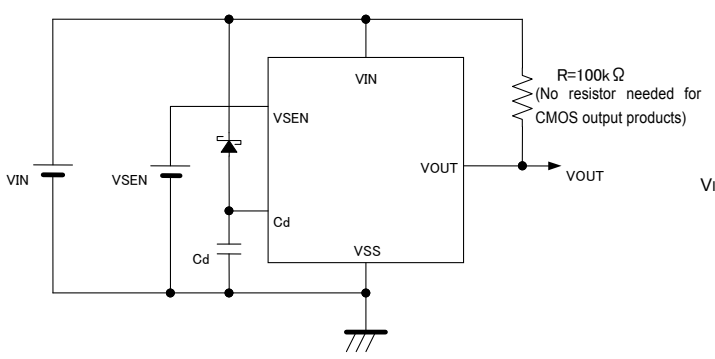
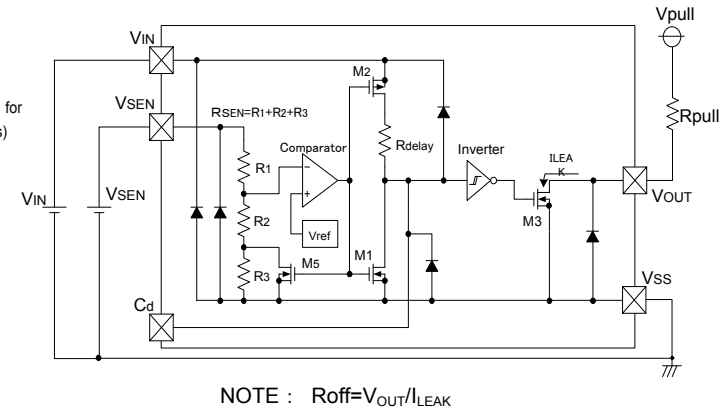


Figure 3

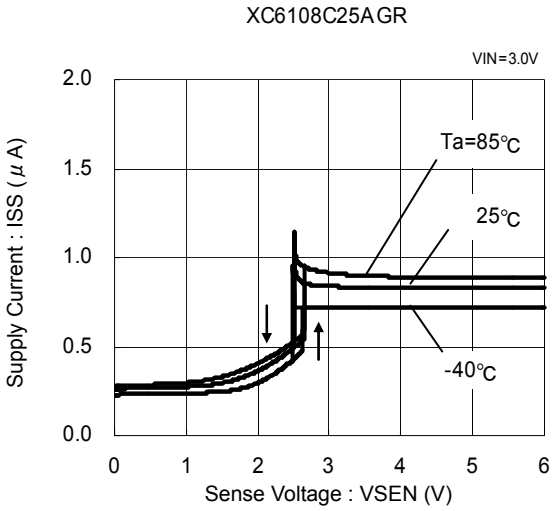


NOTE : Roff=V_{OUT}/I_{LEAK}

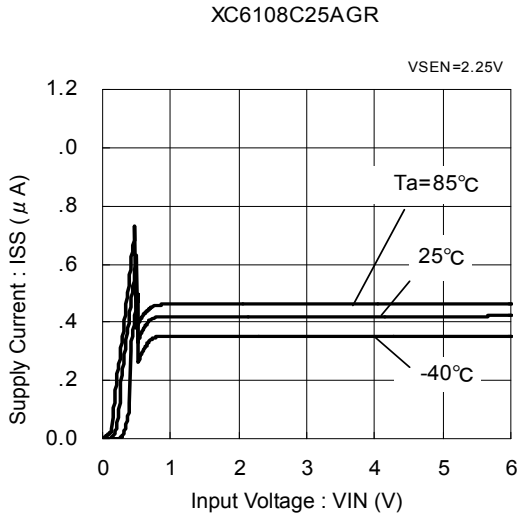
Figure 4

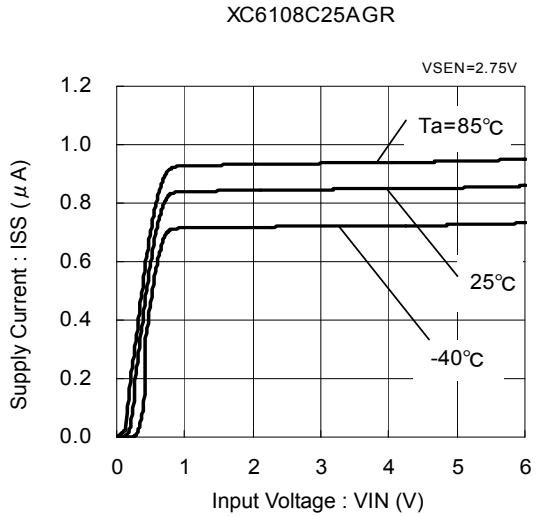
■TYPICAL PERFORMANCE CHARACTERISTICS

(1) Supply Current vs. Sense Voltage

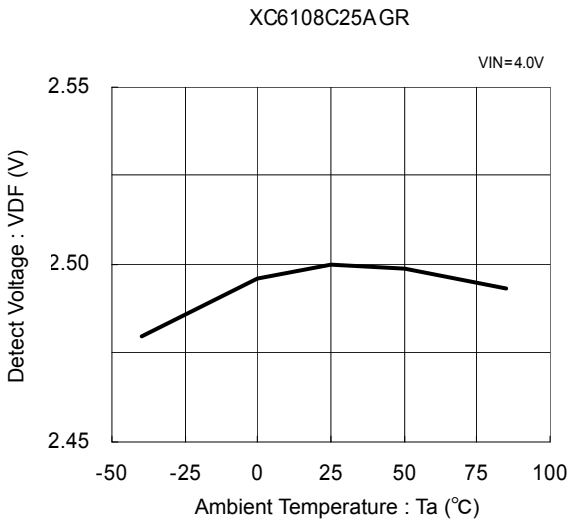


(2) Supply Current vs. Input Voltage

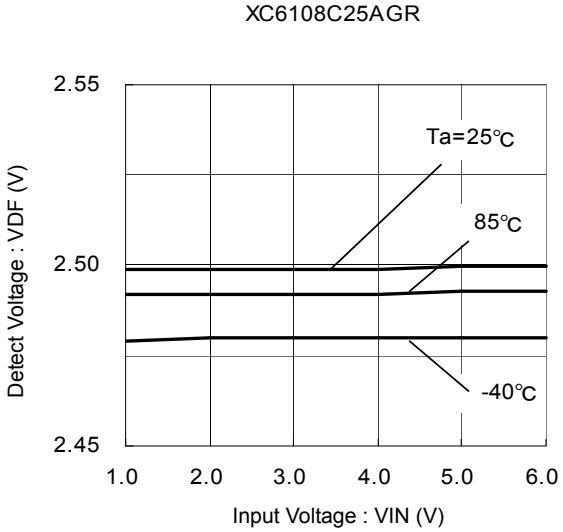




(3) Detect Voltage vs. Ambient Temperature

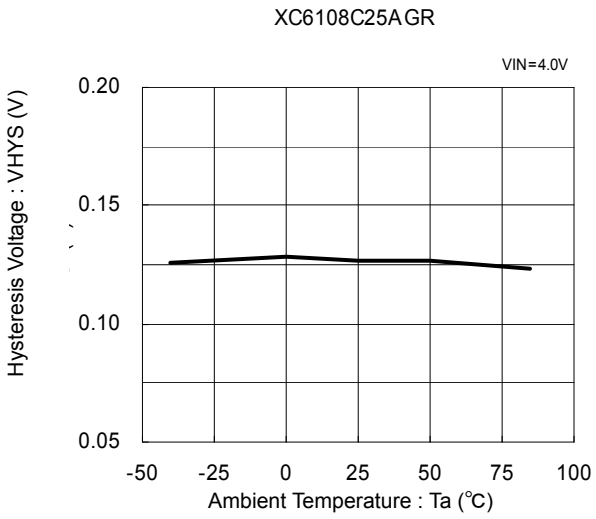


(4) Detect Voltage vs. Input Voltage

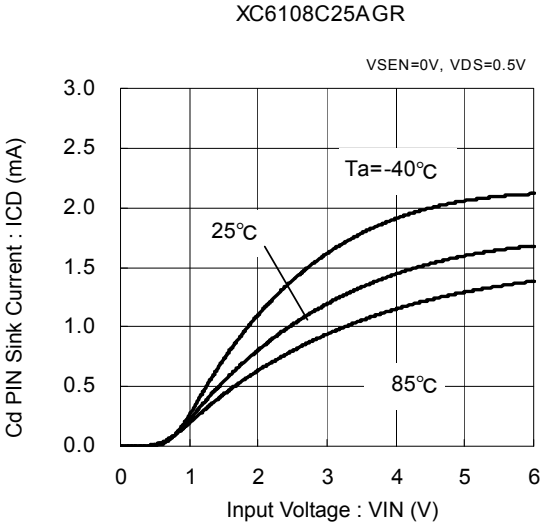


■TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

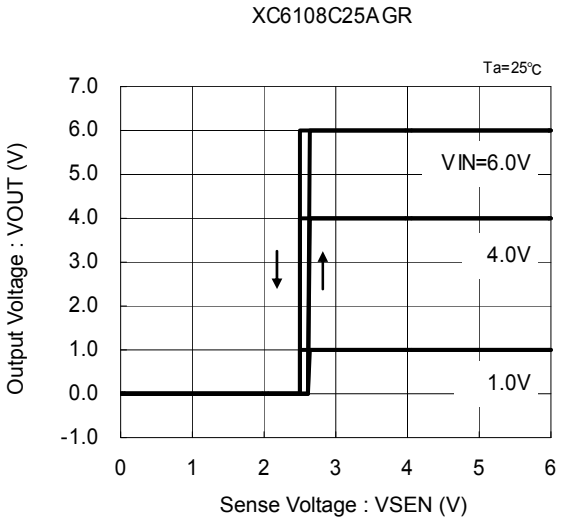
(5) Hysteresis Voltage vs. Ambient Temperature



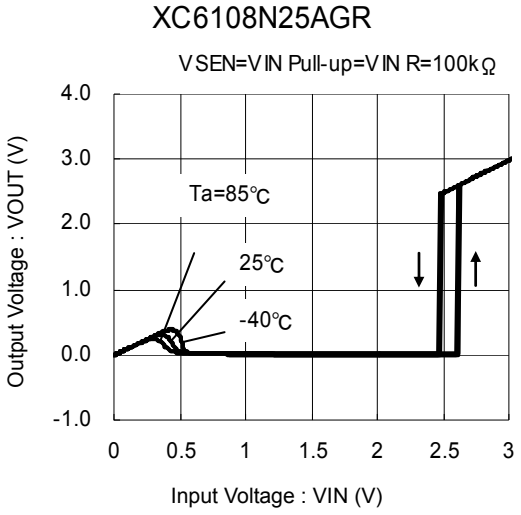
(6) CD Pin Sink Current vs. Input Voltage



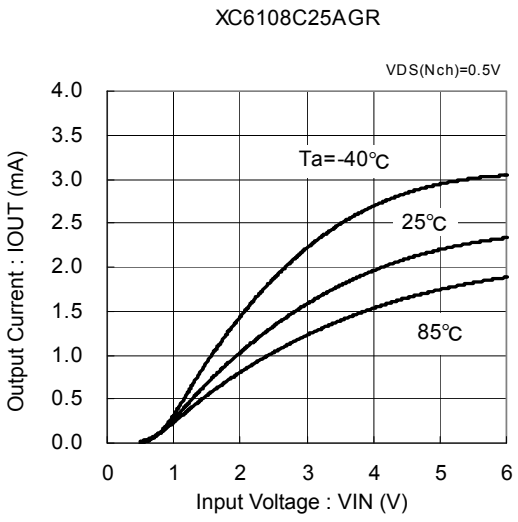
(7) Output Voltage vs. Sense Voltage

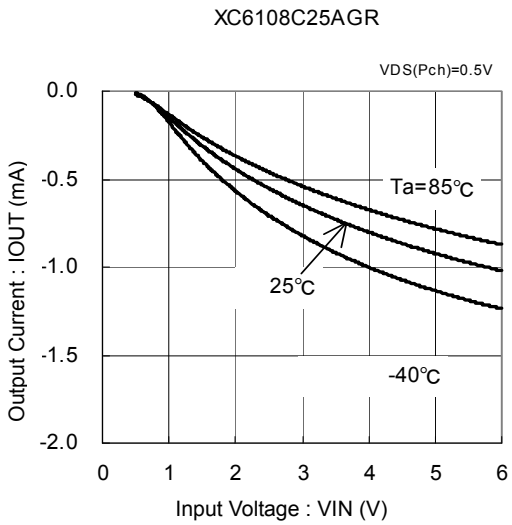


(8) Output Voltage vs. Input Voltage



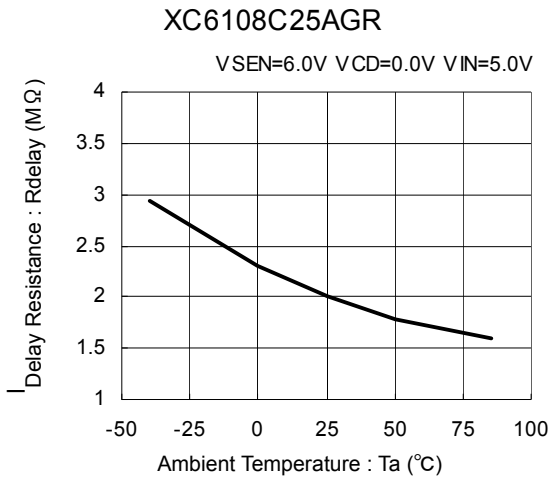
(9) Output Current vs. Input Voltage



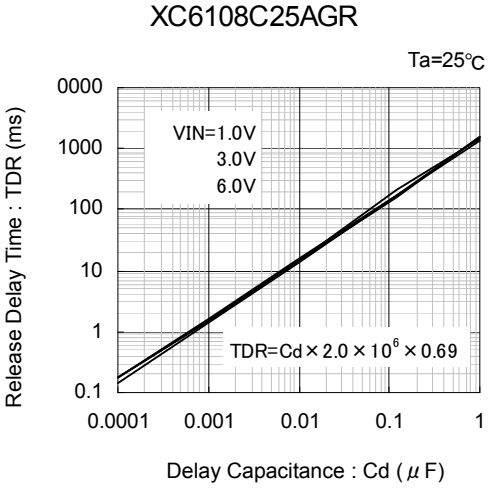


■TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

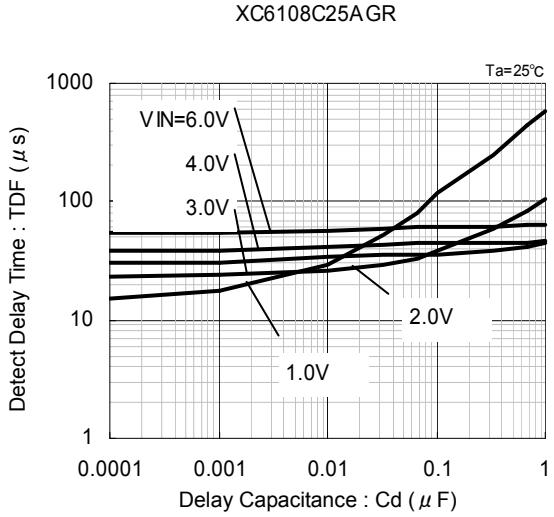
(10) Delay Resistance vs. Ambient Temperature



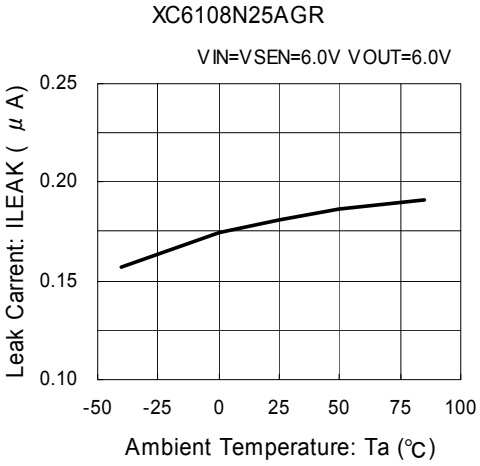
(11) Release Delay Time vs. Delay Capacitance



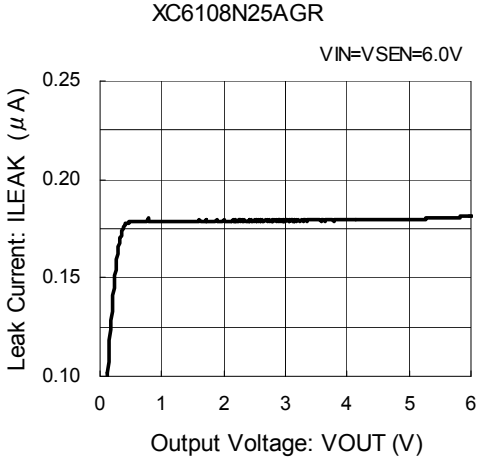
(12) Detect Delay Time vs. Delay Capacitance



(13) Leakage Current vs. Ambient Temperature

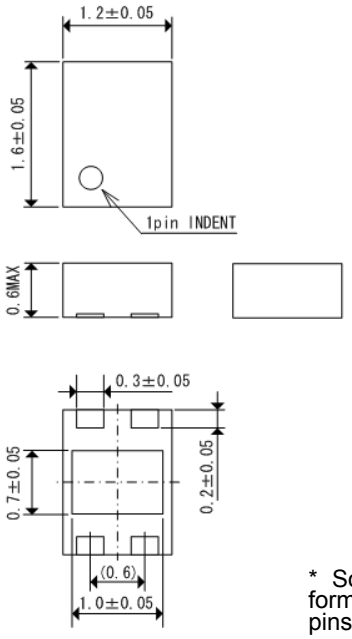


(14) Leakage Current vs. Supply Voltage



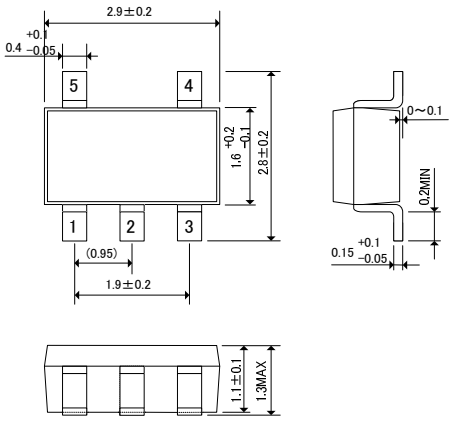
■PACKAGING INFORMATION

●USP-4



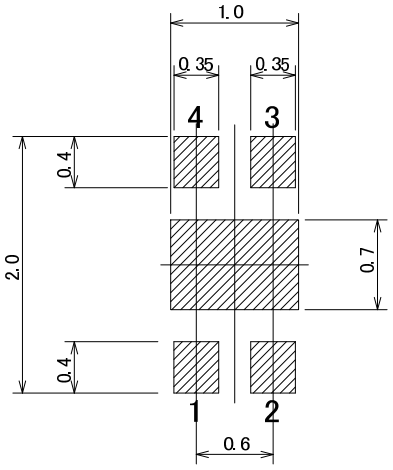
* Soldering fillet surface is not formed because the sides of the pins are plated.

●SOT-25

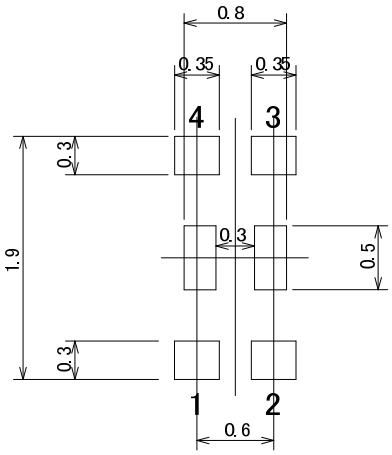


■PACKAGING INFORMATION (Continued)

●USP-4 Reference Pattern Layout

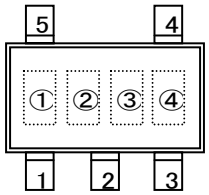


●USP-4 Reference Metal Mask Design



■MARKING RULE

●SOT-25



SOT-25
(TOP VIEW)

① represents output configuration and integer number of detect voltage

CMOS Output (XC6108C Series)

MARK	VOLTAGE (V)
A	0.x
B	1.x
C	2.x
D	3.x
E	4.x
F	5.x

N-ch Open Drain Output (XC6108N Series)

MARK	VOLTAGE (V)
K	0.x
L	1.x
M	2.x
N	3.x
P	4.x
R	5.x

② represents decimal number of detect voltage

(ex.)

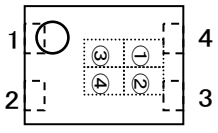
MARK	VOLTAGE (V)	PRODUCT SERIES
3	x.3	XC6108xx3xxx
0	x.0	XC6108xx0xxx

③ represents options

MARK	OPTIONS	PRODUCT SERIES
A	Built-in delay capacitance pin with hysteresis 5% (TYP.) (Standard)	XC6108xxxAxx
B	Built-in delay capacitance pin with hysteresis less than 1% (Standard)	XC6108xxxBxx
C	No built-in delay capacitance pin with hysteresis 5% (TYP.) (Semi-custom)	XC6108xxxCxx
D	No built-in delay capacitance pin with hysteresis less than 1% (Semi-custom)	XC6108xxxDxx

④ represents production lot number
0 to 9, A to Z or inverted characters of 0 to 9, A to Z repeated.
(G, I, J, O, Q, W excluded)

●USP-4



USP-4
(TOP VIEW)

① represents output configuration and integer number of detect voltage

CMOS Output (XC6108C Series)

MARK	VOLTAGE (V)
A	0.x
B	1.x
C	2.x
D	3.x
E	4.x
F	5.x

N-ch Open Drain Output (XC6108N Series)

MARK	VOLTAGE (V)
K	0.x
L	1.x
M	2.x
N	3.x
P	4.x
R	5.x

② represents decimal number of detect voltage

(ex.)

MARK	VOLTAGE (V)	PRODUCT SERIES
3	x.3	XC6108xx3xxx
0	x.0	XC6108xx0xxx

③ represents options

MARK	OPTIONS	PRODUCT SERIES
A	Built-in delay capacitance pin with hysteresis 5% (TYP.) (Standard)	XC6108xxxAxx
B	Built-in delay capacitance pin with hysteresis less than 1% (Standard)	XC6108xxxBxx
C	No built-in delay capacitance pin with hysteresis 5% (TYP.) (Semi-custom)	XC6108xxxCxx
D	No built-in delay capacitance pin with hysteresis less than 1% (Semi-custom)	XC6108xxxDxx

④ represents production lot number
0 to 9, A to Z repeated. (G, I, J, O, Q, W excluded)
*No character inversion used.

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